IXYS

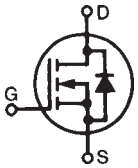
PolarHT™ HiPerFET Power MOSFET

IXFH 74N20P
IXFV 74N20P
IXFV 74N20PS

V_{DSS} = 200 V
I_{D25} = 74 A
$R_{DS(on)}$ = 34 mΩ
t_{rr} ≤ 200 ns

N-Channel Enhancement Mode
Fast Recovery Diode, Avalanche Rated

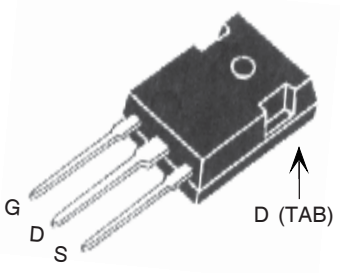
Preliminary Data Sheet



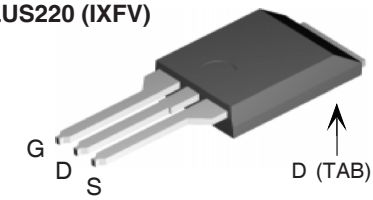
Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	200	V
V_{DGR}	T_J = 25°C to 175°C; R_{GS} = 1 MΩ	200	V
V_{GS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	74	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	200	A
I_{AR}	T_C = 25°C	60	A
E_{AR}	T_C = 25°C	40	mJ
E_{AS}	T_C = 25°C	1.0	J
dv/dt	$I_S \le I_{DM}$, di/dt ≤ 100 A/μs, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$, R_G = 4 Ω	10	V/ns
P_D	T_C = 25°C	480	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C
	Plastic body for 10 s	250	°C
F_C	Mounting Force (PLUS220)	1.13/10	Nm/lb.in.
M_d	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
Weight	TO-247	6.0	g
	PLUS220	4.0	g

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
V_{DSS}	V_{GS} = 0 V, I_D = 250 μA	200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250μA	2.5		5.0	V
I_{GSS}	V_{GS} = ±20 V_{DC}, V_{DS} = 0			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$			25	μA
	V_{GS} = 0 V, T_J = 125°C			250	μA
$R_{DS(on)}$	V_{GS} = 10 V, $I_D = 0.5\ I_{D25}$ Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			34	mΩ

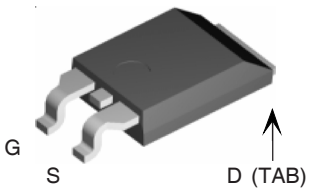
TO-247 (IXFH)



PLUS220 (IXFV)



PLUS220SMD (IXFV-PS)



G = Gate D = Drain
S = Source TAB = Drain

Features

- International standard packages
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect

Advantages

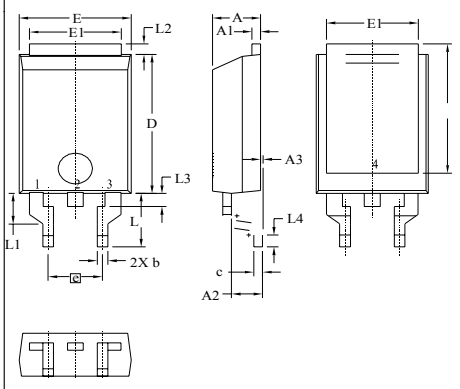
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) Min.	Typ.	Max.	
g_{fs}	V_{DS}= 10 V; I_D = 0.5 I_{D25}, pulse test	30	44		S
C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		3300		pF
C_{oss}			800		pF
C_{rss}			190		pF
$t_{d(on)}$	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = I_{D25} R_G = 4 Ω (External)		23		ns
t_r			21		ns
$t_{d(off)}$			60		ns
t_f			21		ns
$Q_{g(on)}$	V_{GS}= 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}		107		nC
Q_{gs}			24		nC
Q_{gd}			52		nC
R_{thJC}				0.31	K/W
R_{thCK}	(TO-247, PLUS220)		0.21		K/W

Source-Drain Diode

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) Min.	typ.	Max.	
I_S	V_{GS} = 0 V			74	A
I_{SM}	Repetitive			180	A
V_{SD}	I_F = I_S, V_{GS} = 0 V, Pulse test, t ≤ 300 µs, duty cycle d ≤ 2 %			1.5	V
t_{rr}	I_F = 25 A, -di/dt = 100 A/µs		120	200	ns
Q_{RM}	V_R = 100 V		0.4		µC
I_{RM}			6		A

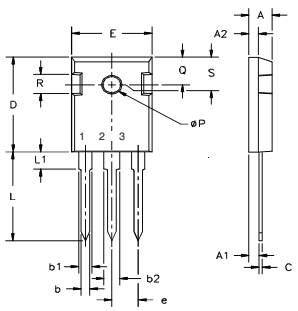
PLUS220SMD (IXFV-PS) Outline



Terminals: 1-Gate 2-Drain

SYM	INCHES MIN	INCHES MAX	MILLIMETER MIN	MILLIMETER MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
A3	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.200BSC		5.08	BSC
L	.209	.228	5.30	5.80
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50
L4	.039	.059	1.00	1.50

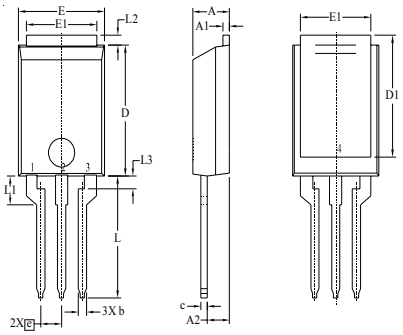
TO-247 (IXFH) Outline



Terminals: 1 - Gate 2 - Drain

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

PLUS220 (IXFV) Outline



Terminals: 1-Gate 2-Drain

SYM	INCHES MIN	INCHES MAX	MILLIMETER MIN	MILLIMETER MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
b	.035	.047	0.90	1.20
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.100 BSC		2.54	BSC
L	.512	.551	13.00	14.00
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50

Fig. 1. Output Characteristics @ 25ºC

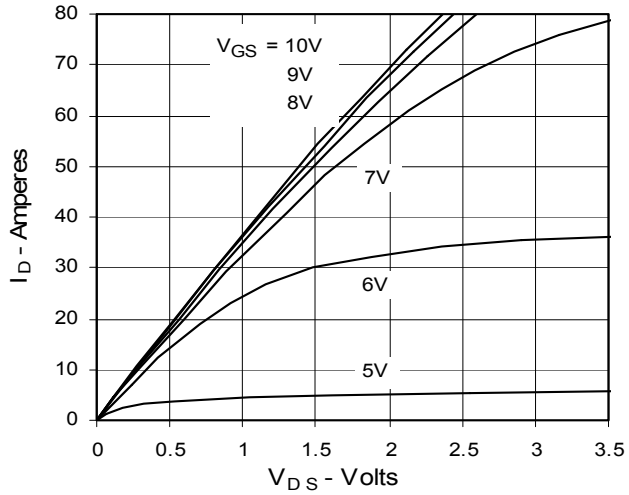


Fig. 2. Extended Output Characteristics @ 25ºC

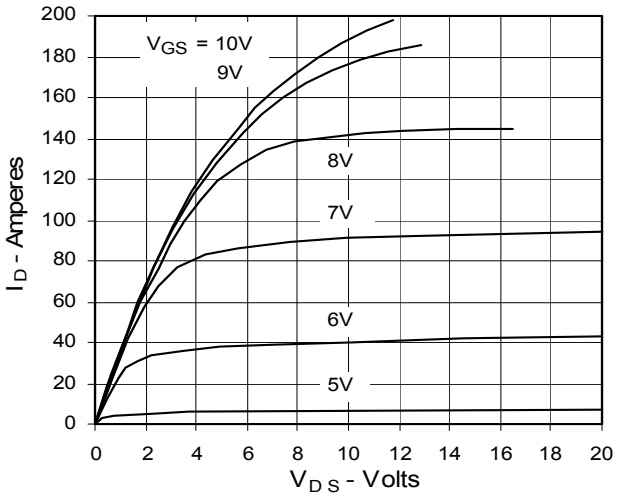


Fig. 3. Output Characteristics @ 150ºC

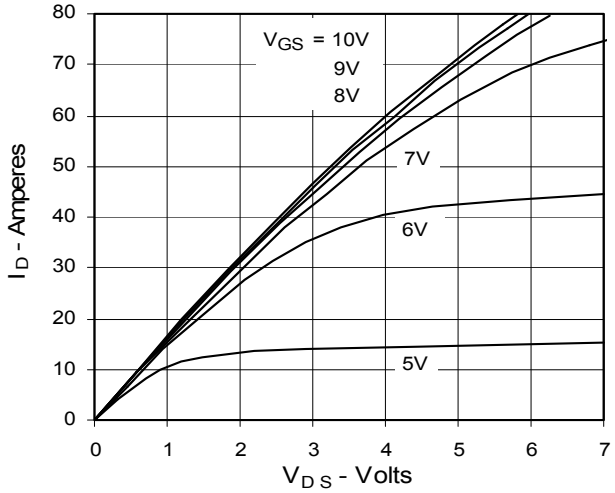


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

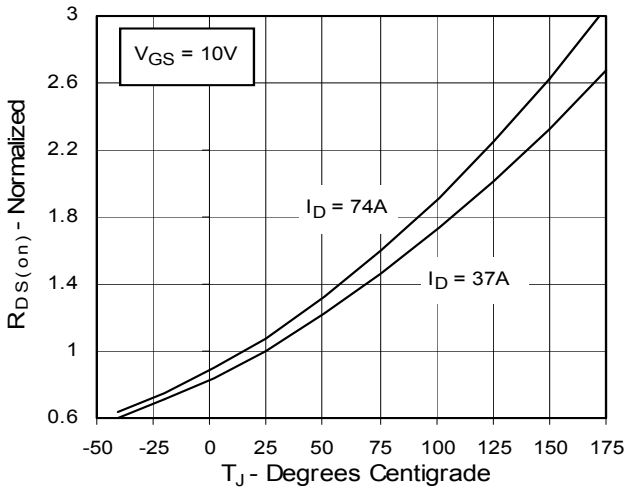


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. I_D

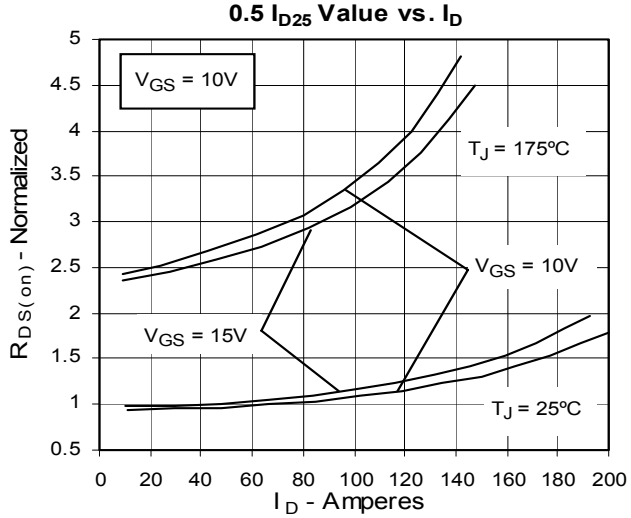


Fig. 6. Drain Current vs. Case Temperature

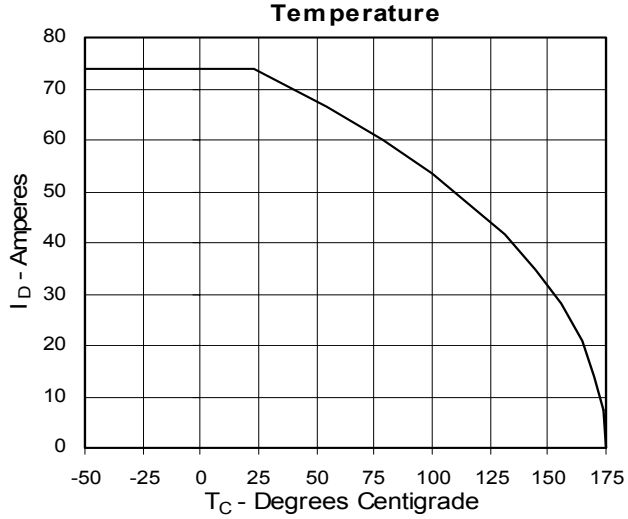


Fig. 7. Input Admittance

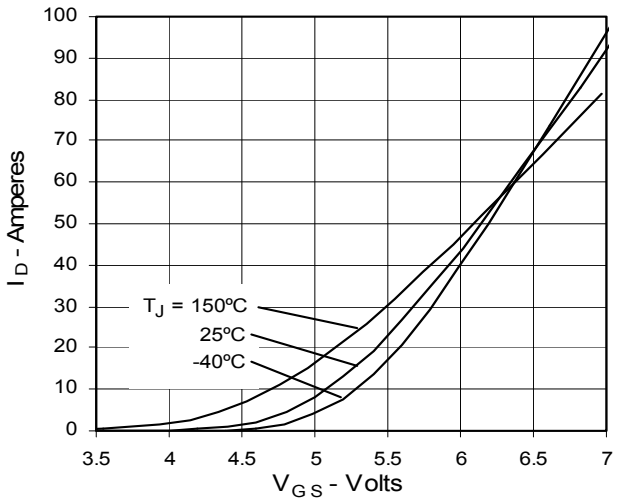


Fig. 8. Transconductance

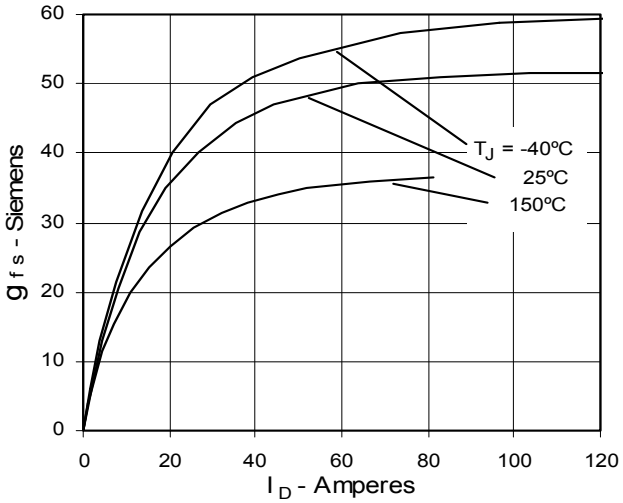


Fig. 9. Source Current vs. Source-To-Drain Voltage

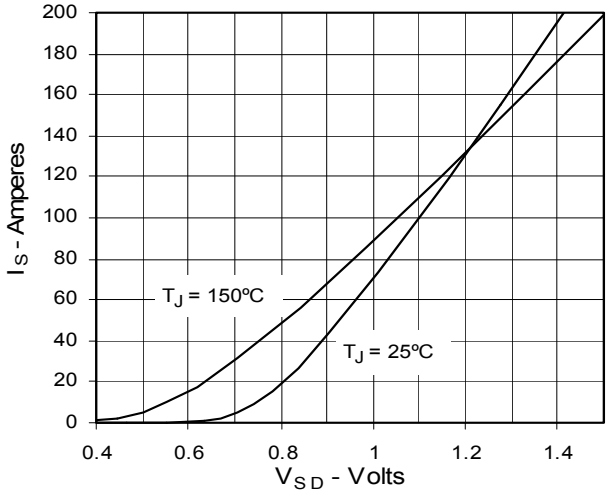


Fig. 10. Gate Charge

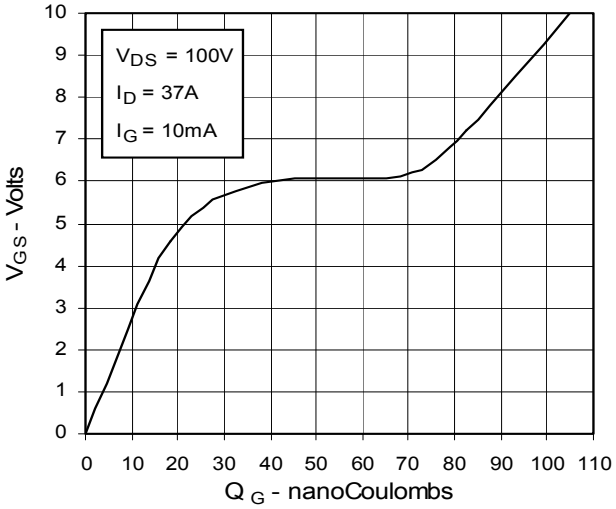


Fig. 11. Capacitance

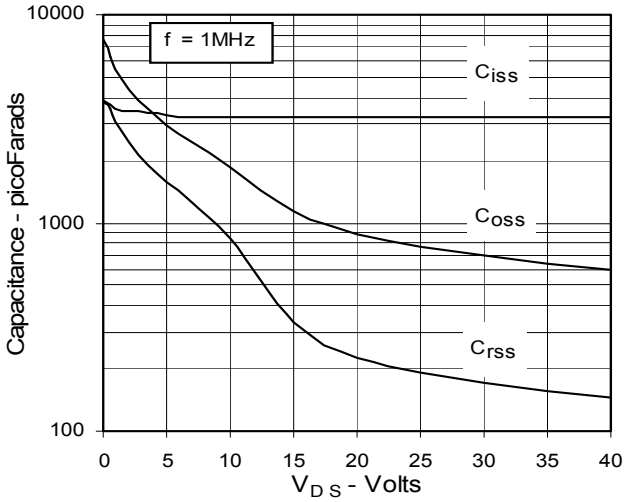


Fig. 12. Forward-Bias Safe Operating Area

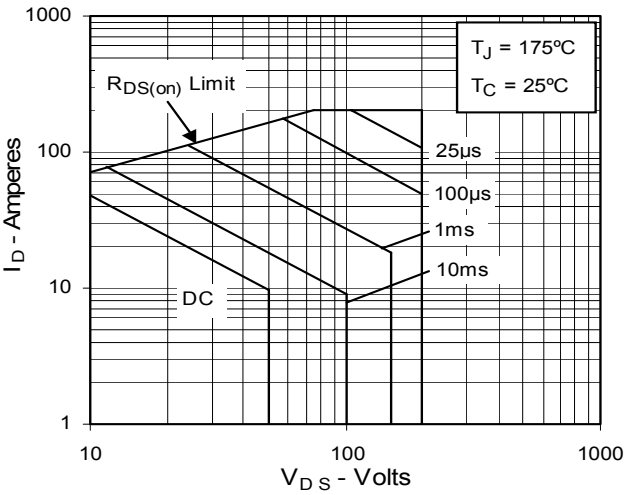


Fig. 13. Maximum Transient Thermal Resistance